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Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc712t-04i-ss

2.0 MEMORY ORGANIZATION

There are two memory blocks in each of these PIC[®] microcontroller devices. Each block (Program Memory and Data Memory) has its own bus so that concurrent access can occur.

Additional information on device memory may be found in the PIC[®] Mid-Range Reference Manual, (DS33023).

2.1 Program Memory Organization

The PIC16C712/716 has a 13-bit Program Counter (PC) capable of addressing an 8K x 14 program memory space. PIC16C712 has 1K x 14 words of program memory and PIC16C716 has 2K x 14 words of program memory. Accessing a location above the physically implemented address will cause a wraparound.

The Reset vector is at 0000h and the interrupt vector is at 0004h.

FIGURE 2-1: PROGRAM MEMORY MAP AND STACK OF THE PIC16C712

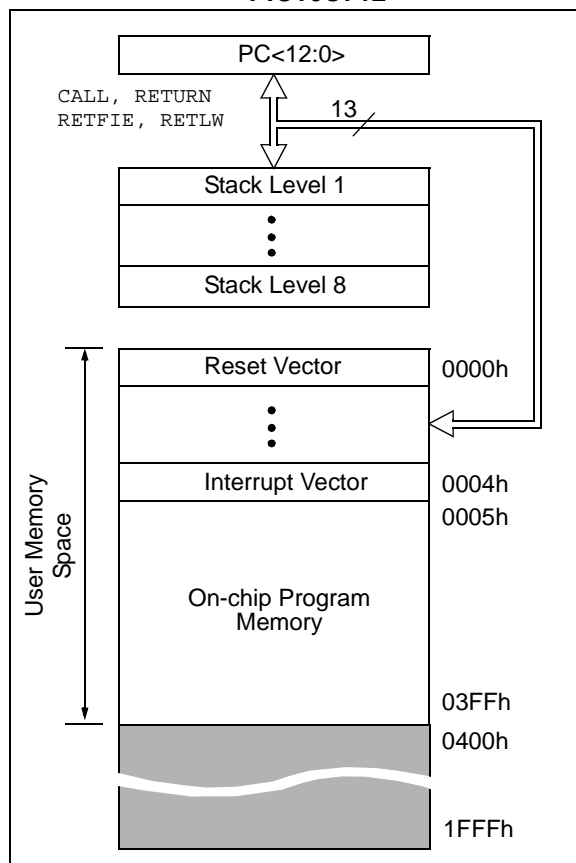
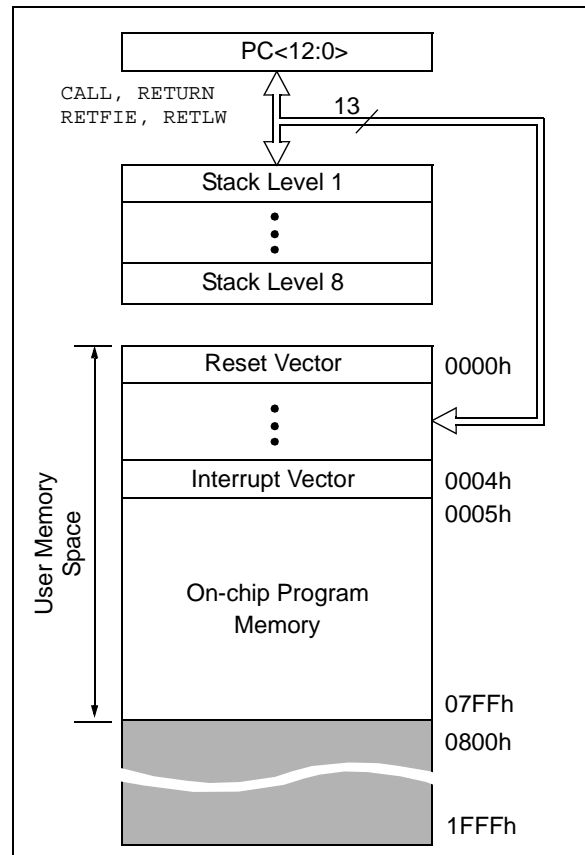


FIGURE 2-2: PROGRAM MEMORY MAP AND STACK OF PIC16C716



2.2.2.3 INTCON Register

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts.

Note: Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-6: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x
GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF
bit7							bit0
<p>bit 7: GIE: Global Interrupt Enable bit 1 = Enables all unmasked interrupts 0 = Disables all interrupts</p> <p>bit 6: PEIE: Peripheral Interrupt Enable bit 1 = Enables all unmasked peripheral interrupts 0 = Disables all peripheral interrupts</p> <p>bit 5: TOIE: TMR0 Overflow Interrupt Enable bit 1 = Enables the TMR0 interrupt 0 = Disables the TMR0 interrupt</p> <p>bit 4: IINTE: RB0/INT External Interrupt Enable bit 1 = Enables the RB0/INT external interrupt 0 = Disables the RB0/INT external interrupt</p> <p>bit 3: RBIE: RB Port Change Interrupt Enable bit 1 = Enables the RB port change interrupt 0 = Disables the RB port change interrupt</p> <p>bit 2: TOIF: TMR0 Overflow Interrupt Flag bit 1 = TMR0 register has overflowed (must be cleared in software) 0 = TMR0 register did not overflow</p> <p>bit 1: INTF: RB0/INT External Interrupt Flag bit 1 = The RB0/INT external interrupt occurred (must be cleared in software) 0 = The RB0/INT external interrupt did not occur</p> <p>bit 0: RBIF: RB Port Change Interrupt Flag bit 1 = At least one of the RB7:RB4 pins changed state (must be cleared in software) 0 = None of the RB7:RB4 pins have changed state</p>							
<p>R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' -n = Value at POR Reset</p>							

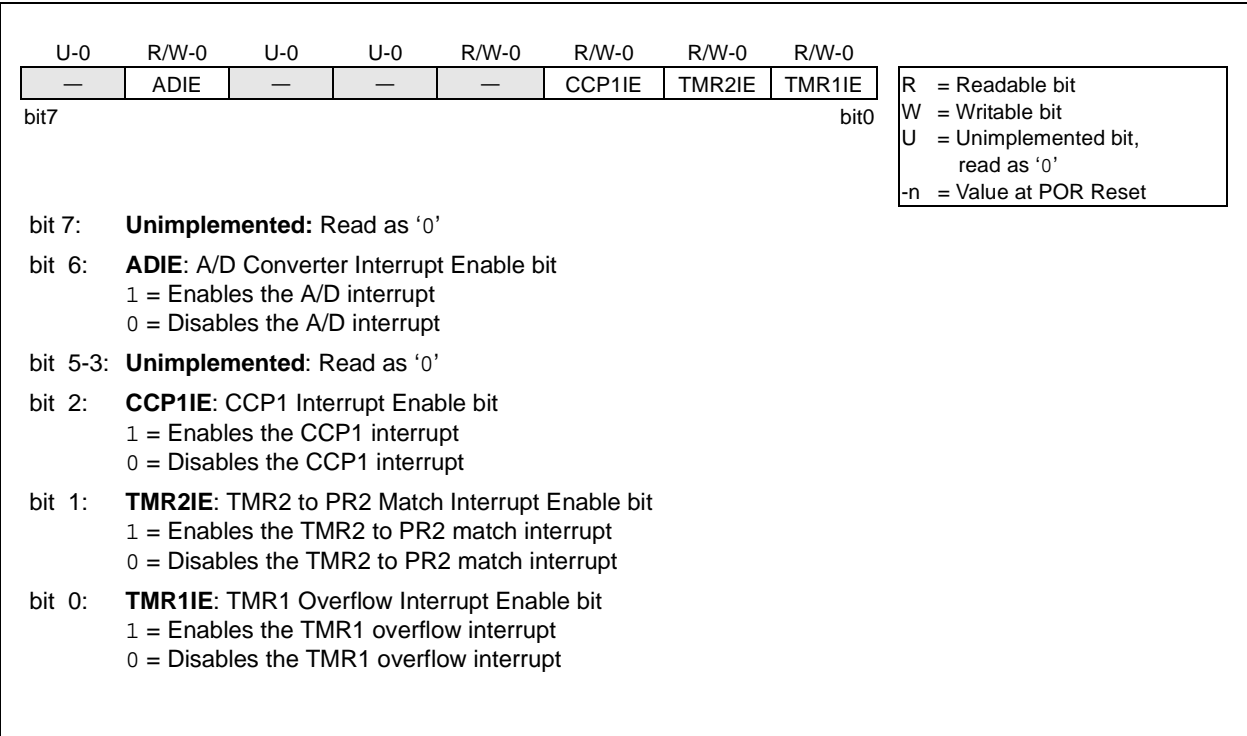
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2.2.2.4 PIE1 Register

This register contains the individual enable bits for the peripheral interrupts.

Note: Bit PEIE (INTCON<6>) must be set to enable any peripheral interrupt.

FIGURE 2-7: PIE1 REGISTER (ADDRESS 8Ch)



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NOTES:

7.0 CAPTURE/COMPARE/PWM (CCP) MODULE(S)

Each CCP (Capture/Compare/PWM) module contains a 16-bit register, which can operate as a 16-bit capture register, as a 16-bit compare register or as a PWM master/slave Duty Cycle register. Table 7-1 shows the timer resources of the CCP module modes.

Capture/Compare/PWM Register 1 (CCPR1) is comprised of two 8-bit registers: CCPR1L (low byte) and CCPR1H (high byte). The CCP1CON register controls the operation of CCP1. All are readable and writable.

Additional information on the CCP module is available in the PIC® Mid-Range Reference Manual, (DS33023).

TABLE 7-1: CCP MODE – TIMER RESOURCE

CCP Mode	Timer Resource
Capture	Timer1
Compare	Timer1
PWM	Timer2

FIGURE 7-1: CCP1CON REGISTER (ADDRESS 17h)

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-6: **Unimplemented:** Read as '0'

bit 5-4: **DC1B1:DC1B0:** PWM Least Significant bits
Capture Mode: Unused
Compare Mode: Unused
PWM Mode: These bits are the two LSBs of the PWM duty cycle. The eight MSBs are found in CCPR1L.

bit 3-0: **CCP1M3:CCP1M0:** CCP1 Mode Select bits
0000 = Capture/Compare/PWM off (resets CCP1 module)
0100 = Capture mode, every falling edge
0101 = Capture mode, every rising edge
0110 = Capture mode, every 4th rising edge
0111 = Capture mode, every 16th rising edge
1000 = Compare mode, set output on match (CCP1IF bit is set)
1001 = Compare mode, clear output on match (CCP1IF bit is set)
1010 = Compare mode, generate software interrupt on match (CCP1IF bit is set, CCP1 pin is unaffected)
1011 = Compare mode, trigger special event (CCP1IF bit is set; CCP1 resets TMR1 and starts an A/D conversion (if A/D module is enabled))
11xx = PWM mode

FIGURE 7-2: TRISCCP REGISTER (ADDRESS 87H)

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	—	—	TCCP	—	TT1CK
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-3: **Reserved bits; Do Not Use**

bit 2: **TCCP – Tri-state control bit for CCP**
0 = Output pin driven
1 = Output pin tristated

bit 1: **Reserved bit; Do Not Use**

bit 0: **TT1CK – Tri-state control bit for T1CKI pin**
0 = T1CKI pin is an output
1 = T1CKI pin is an input

8.0 ANALOG-TO-DIGITAL CONVERTER (A/D) MODULE

The Analog-to-Digital (A/D) Converter module has four inputs.

The A/D allows conversion of an analog input signal to a corresponding 8-bit digital number (refer to Application Note AN546 for use of A/D Converter). The output of the sample and hold is the input into the converter, which generates the result via successive approximation. The analog reference voltage is software selectable to either the device's positive supply voltage (V_{DD}) or the voltage level on the RA3/AN3/VREF pin.

The A/D converter has a unique feature of being able to operate while the device is in Sleep mode. To operate in Sleep, the A/D conversion clock must be derived from the A/D's internal RC oscillator.

Additional information on the A/D module is available in the PIC® Mid-Range Reference Manual, (DS33023).

The A/D module has three registers. These registers are:

- A/D Result Register (ADRES)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)

A device Reset forces all registers to their Reset state. This forces the A/D module to be turned off, and any conversion is aborted.

The ADCON0 register, shown in Figure 8-1, controls the operation of the A/D module. The ADCON1 register, shown in Figure 8-2, configures the functions of the port pins. The port pins can be configured as analog inputs (RA3 can also be a voltage reference) or as digital I/O.

FIGURE 8-1: ADCON0 REGISTER (ADDRESS 1Fh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-6: **ADCS1:ADCS0:** A/D Conversion Clock Select bits
00 = $F_{OSC}/2$
01 = $F_{OSC}/8$
10 = $F_{OSC}/32$
11 = FRC (clock derived from the internal ADC RC oscillator)

bit 5-3: **CHS2:CHS0:** Analog Channel Select bits
000 = channel 0, (RA0/AN0)
001 = channel 1, (RA1/AN1)
010 = channel 2, (RA2/AN2)
011 = channel 3, (RA3/AN3)
1xx = reserved, do not use

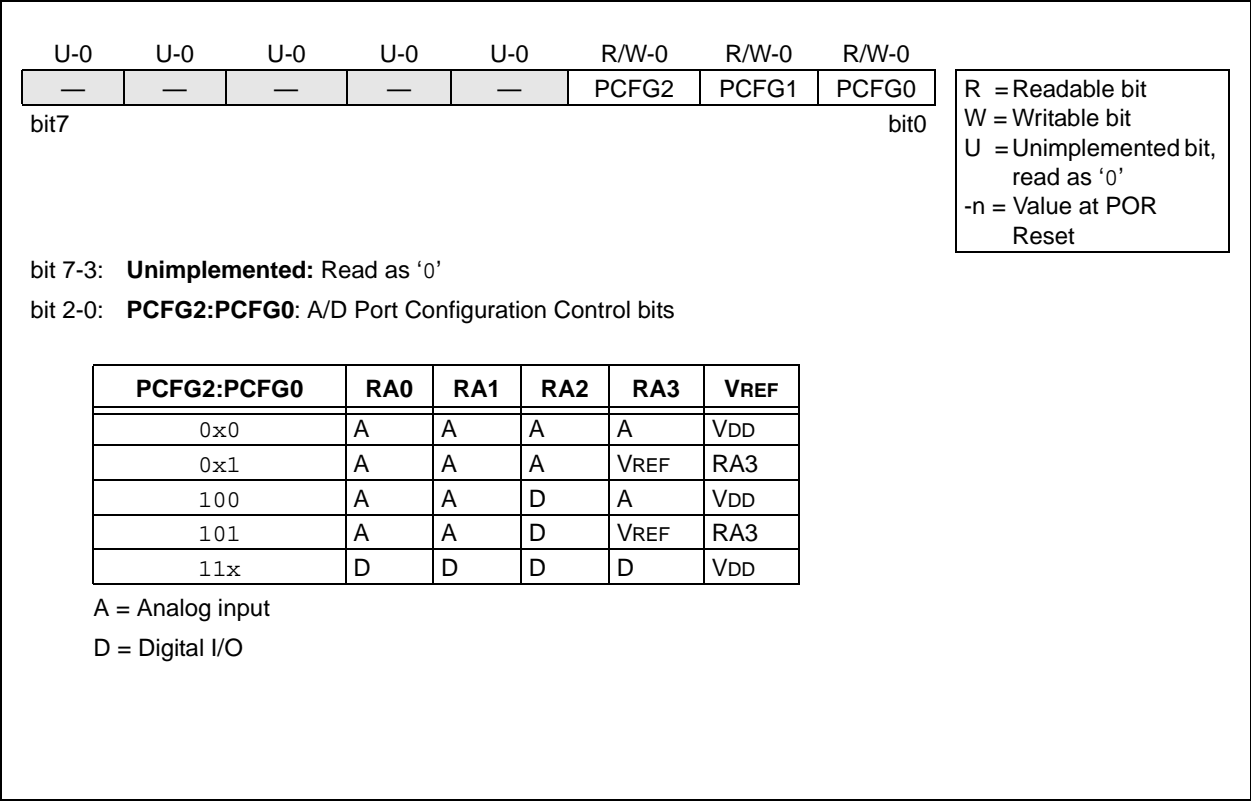
bit 2: **GO/DONE:** A/D Conversion Status bit
If **ADON** = 1
1 = A/D conversion in progress (setting this bit starts the A/D conversion)
0 = A/D conversion not in progress (This bit is automatically cleared by hardware when the A/D conversion is complete)

bit 1: **Unimplemented:** Read as '0'

bit 0: **ADON:** A/D On bit
1 = A/D converter module is operating
0 = A/D converter module is shutoff and consumes no operating current

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FIGURE 8-2: ADCON1 REGISTER (ADDRESS 9Fh)



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8.4 A/D Conversions

Note: The GO/DONE bit should **NOT** be set in the same instruction that turns on the A/D.

8.5 Use of the CCP Trigger

An A/D conversion can be started by the “Special Event Trigger” of the CCP1 module. This requires that the CCP1M3:CCP1M0 bits (CCP1CON<3:0>) be programmed as 1011 and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the

GO/DONE bit will be set, starting the A/D conversion, and the Timer1 counter will be reset to zero. Timer1 is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving the ADRES to the desired location). The appropriate analog input channel must be selected and the minimum acquisition done before the “Special Event Trigger” sets the GO/DONE bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), then the “Special Event Trigger” will be ignored by the A/D module, but will still reset the Timer1 counter.

TABLE 8-2: SUMMARY OF A/D REGISTERS

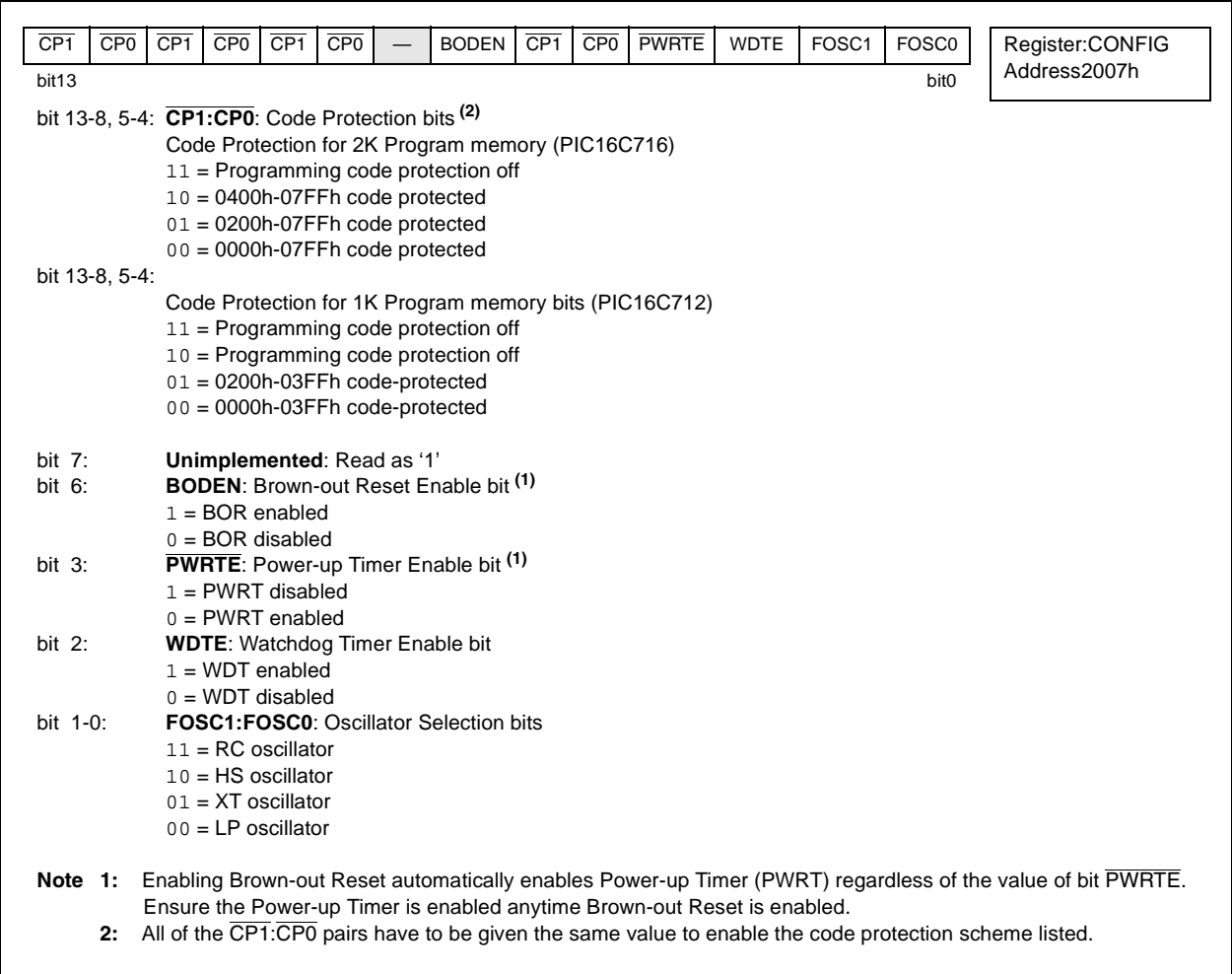
Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
05h	PORTA	—	—	— ⁽¹⁾	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--xu uuuu
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0-- -000	-0-- -000
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/DONE	—	ADON	0000 00-0	0000 00-0
85h	TRISA	—	—	— ⁽¹⁾	PORTA Data Direction Register					---1 1111	---1 1111
8Ch	PIE1	—	ADIE	—	—	—	CCP1IE	TMR2IE	TMR1IE	-0-- -000	-0-- 0000
9Fh	ADCON1	—	—	—	—	—	PCFG2	PCFG1	PCFG0	---- -000	---- -000

Legend: x = unknown, u = unchanged, — = unimplemented read as ‘0’. Shaded cells are not used for A/D conversion.

Note 1: Reserved bits; Do Not Use.

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FIGURE 9-1: CONFIGURATION WORD



12.3 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended) PIC16LC712/716-04 (Commercial, Industrial)

Standard Operating Conditions (unless otherwise stated) Operating temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage V_{DD} range as described in DC spec Section 12.1 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)” and Section 12.2 “DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)”							
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D030 D030A D031 D032 D033	V_{IL}	Input Low Voltage I/O ports with TTL buffer with Schmitt Trigger buffer $\overline{\text{MCLR}}$, OSC1 (in RC mode) OSC1 (in XT, HS and LP modes)	V_{SS} V_{SS} V_{SS} V_{SS} V_{SS}	— — — — —	0.8V 0.15 V_{DD} 0.2 V_{DD} 0.2 V_{DD} 0.3 V_{DD}	V V V V V	$4.5\text{V} \leq V_{DD} \leq 5.5\text{V}$ otherwise (Note 1)
D040 D040A D041 D042 D042A D043	V_{IH}	Input High Voltage I/O ports with TTL buffer with Schmitt Trigger buffer $\overline{\text{MCLR}}$ OSC1 (XT, HS and LP modes) OSC1 (in RC mode)	2.0 0.25 V_{DD} + 0.8V 0.8 V_{DD} 0.8 V_{DD} 0.7 V_{DD} 0.9 V_{DD}	— — — — — — —	V_{DD} V_{DD} V_{DD} V_{DD} V_{DD} V_{DD}	V V V V V V	$4.5\text{V} \leq V_{DD} \leq 5.5\text{V}$ otherwise For entire V_{DD} range (Note 1)
D060 D061 D063	I_{IL}	Input Leakage Current (Notes 2, 3) I/O ports $\overline{\text{MCLR}}$, RA4/T0CKI OSC1	— — —	— — —	± 1 ± 5 ± 5	μA μA μA	$V_{SS} \leq V_{PIN} \leq V_{DD}$, Pin at high-impedance $V_{SS} \leq V_{PIN} \leq V_{DD}$ $V_{SS} \leq V_{PIN} \leq V_{DD}$, XT, HS and LP osc modes
D070	I_{PURB}	PORTB weak pull-up current	50	250	400	μA	$V_{DD} = 5\text{V}$, $V_{PIN} = V_{SS}$

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ / V_{PP} pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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Standard Operating Conditions (unless otherwise stated) Operating temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended Operating voltage V_{DD} range as described in DC spec Section 12.1 “DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712/716-20 (Commercial, Industrial, Extended)” and Section 12.2 “DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)”							
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
D080	VOL	Output Low Voltage I/O ports	—	—	0.6	V	$I_{OL} = 8.5\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+85^{\circ}\text{C}$ $I_{OL} = 7.0\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+125^{\circ}\text{C}$ $I_{OL} = 1.6\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+85^{\circ}\text{C}$ $I_{OL} = 1.2\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+125^{\circ}\text{C}$
D083		OSC2/CLKOUT (RC Osc mode)	—	—	0.6	V	
			—	—	0.6	V	
			—	—	0.6	V	
D090	VOH	Output High Voltage I/O ports (Note 3)	$V_{DD}-0.7$	—	—	V	$I_{OH} = -3.0\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+85^{\circ}\text{C}$ $I_{OH} = -2.5\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+125^{\circ}\text{C}$ $I_{OH} = -1.3\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+85^{\circ}\text{C}$ $I_{OH} = -1.0\text{ mA}$, $V_{DD} = 4.5\text{V}$, -40°C to $+125^{\circ}\text{C}$
			$V_{DD}-0.7$	—	—	V	
D092		OSC2/CLKOUT (RC Osc mode)	$V_{DD}-0.7$	—	—	V	
			$V_{DD}-0.7$	—	—	V	
D150*	VOD	Open-Drain High Voltage	—	—	8.5	V	RA4 pin
		Capacitive Loading Specs on Output Pins					
D100	Cosc2	OSC2 pin	—	—	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.
D101	Cio	All I/O pins and OSC2 (in RC mode)	—	—	50	pF	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}/\text{VPP}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

FIGURE 12-9: CAPTURE/COMPARE/PWM TIMINGS

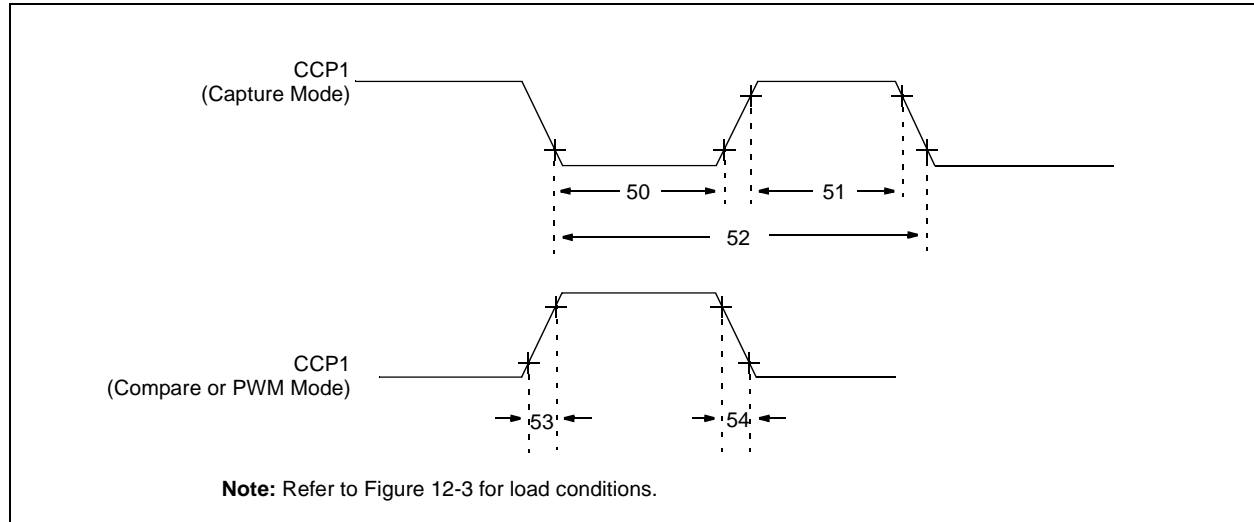


TABLE 12-6: CAPTURE/COMPARE/PWM REQUIREMENTS

Param No.	Sym.	Characteristic		Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler					
			Standard	10	—	—	ns	
			Extended (LC)	20	—	—	ns	
51*	TccH	CCP1 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler					
			Standard	10	—	—	ns	
			Extended (LC)	20	—	—	ns	
52*	TccP	CCP1 input period		$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4, or 16)
53*	TccR	CCP1 output rise time	Standard	—	10	25	ns	
			Extended (LC)	—	25	45	ns	
54*	TccF	CCP1 output fall time	Standard	—	10	25	ns	
			Extended (LC)	—	25	45	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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TABLE 12-7: A/D CONVERTER CHARACTERISTICS:
PIC16C712/716-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C712/716-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16LC712/716-04 (COMMERCIAL, INDUSTRIAL)

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
A01	NR	Resolution	—	—	8-bits	bit	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A02	EABS	Total Absolute error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A03	EIL	Integral linearity error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A04	EDL	Differential linearity error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A05	EFS	Full scale error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A06	EOFF	Offset error	—	—	< ± 1	LSb	VREF = VDD = 5.12V, VSS ≤ VAIN ≤ VREF
A10	—	Monotonicity	—	guaranteed (Note 3)	—	—	VSS ≤ VAIN ≤ VREF
A20	VREF	Reference voltage	2.5V	—	VDD + 0.3	V	
A25	VAIN	Analog input voltage	VSS - 0.3	—	VREF + 0.3	V	
A30	ZAIN	Recommended impedance of analog voltage source	—	—	10.0	kΩ	
A40	IAD	A/D conversion current (VDD)	Standard	—	180	—	μA
			Extended (LC)	—	90	—	
A50	IREF	VREF input current (Note 2)	10	—	1000	μA	During VAIN acquisition. Based on differential of VHOLD to VAIN to charge CHOLD, see Section 9.1 “Configuration Bits” . During A/D Conversion cycle
			—	—	10	μA	

2: * These parameters are characterized but not tested.

3: † Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.
The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

3: The A/D conversion result never decreases with an increase in the Input Voltage, and has no missing codes.

FIGURE 12-10: A/D CONVERSION TIMING

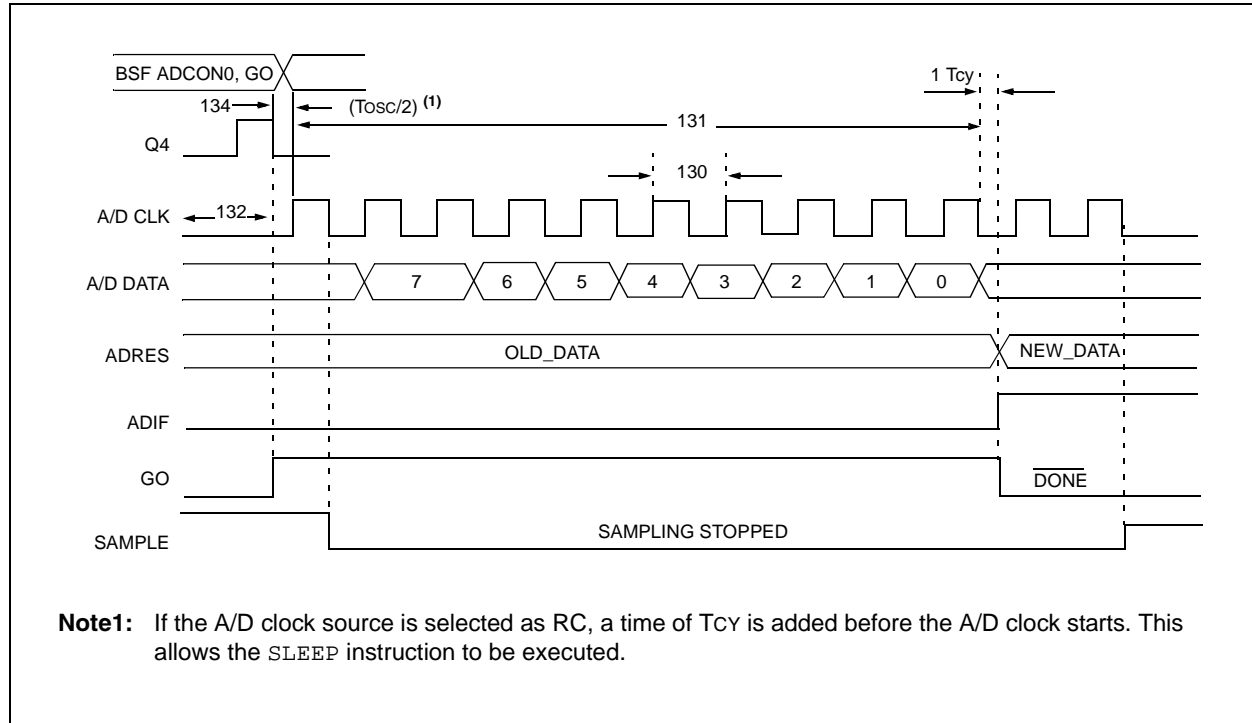


TABLE 12-8: A/D CONVERSION REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
130	TAD	A/D clock period	Standard	1.6	—	—	μs	TOSC based, $V_{REF} \geq 3.0V$
			Extended (LC)	2.0	—	—	μs	TOSC based, V_{REF} full range
			Standard	2.0	4.0	6.0	μs	A/D RC Mode
			Extended (LC)	3.0	6.0	9.0	μs	A/D RC Mode
131	Tcnv	Conversion time (not including S/H time) (Note 1)		11	—	11	TAD	
132	TACQ	Acquisition time		(Note 2)	20	—	μs	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSB (i.e., 20.0 mV @ 5.12V) from the last sampled voltage (as stated on CHOLD).
				5*	—	—	μs	
134	Tgo	Q4 to A/D clock start		—	$T_{osc}/2$ §	—	—	If the A/D clock source is selected as RC, a time of T_{CY} is added before the A/D clock starts. This allows the <i>SLEEP</i> instruction to be executed.
135	Tswc	Switching from convert \overline{AE} sample time		1.5 §	—	—	TAD	

: * These parameters are characterized but not tested.

: † Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

: § This specification ensured by design.

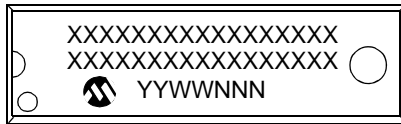
Note 1: ADRES register may be read on the following T_{CY} cycle.

2: See **Section 9.1 "Configuration Bits"** for min. conditions.

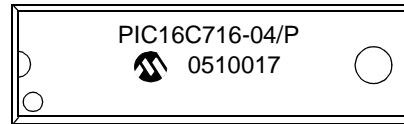
13.0 PACKAGING INFORMATION

13.1 Package Marking Information

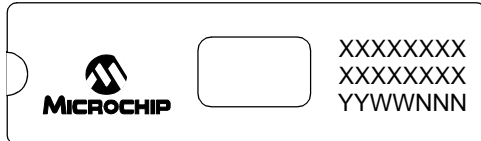
18-Lead PDIP



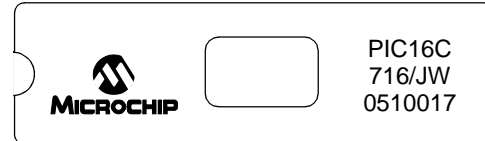
Example



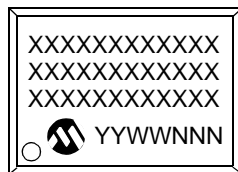
18-Lead CERDIP Windowed



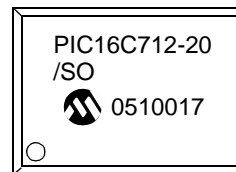
Example



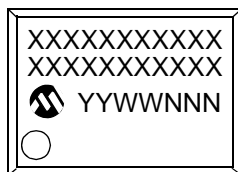
18-Lead SOIC (.300")



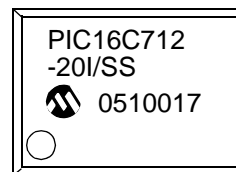
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

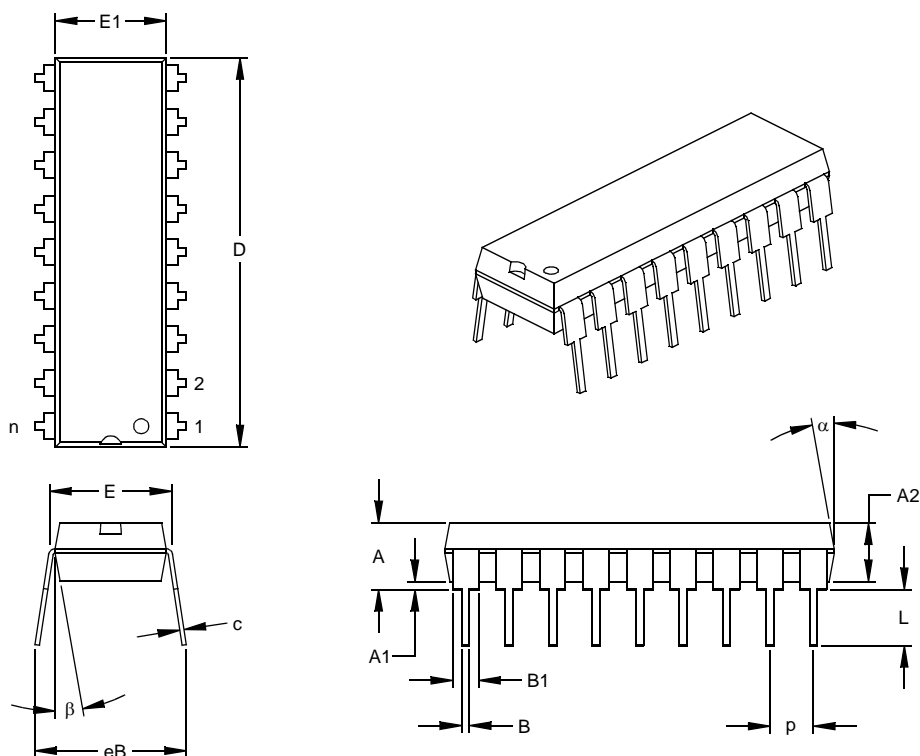
PIC16C712/716

13.2 Package Details

The following sections give the technical details of the packages.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-007

APPENDIX A: REVISION HISTORY

Version	Date	Revision Description
A	2/99	This is a new data sheet. However, the devices described in this data sheet are the upgrades to the devices found in the <i>PIC16C6X Data Sheet</i> , DS30234, and the <i>PIC16C7X Data Sheet</i> , DS30390.
B	9/05	Removed Preliminary Status.
C	1/13	Added a note to each package outline drawing.

APPENDIX B: CONVERSION CONSIDERATIONS

There are no previous versions of this device.

APPENDIX C: MIGRATION FROM BASE-LINE TO MID-RANGE DEVICES

This section discusses how to migrate from a baseline device (i.e., PIC16C5X) to a mid-range device (i.e., PIC16CXXX).

The following are the list of modifications over the PIC16C5X microcontroller family:

1. Instruction word length is increased to 14-bits. This allows larger page sizes both in program memory (2K now as opposed to 512 before) and register file (128 bytes now versus 32 bytes before).
2. A PC high latch register (PCLATH) is added to handle program memory paging. Bits PA2, PA1, PA0 are removed from STATUS register.
3. Data memory paging is redefined slightly. STATUS register is modified.
4. Four new instructions have been added: RETURN, RETFIE, ADDLW, and SUBLW. Two instructions TRIS and OPTION are being phased out although they are kept for compatibility with PIC16C5X.
5. OPTION_REG and TRIS registers are made addressable.
6. Interrupt capability is added. Interrupt vector is at 0004h.
7. Stack size is increased to 8 deep.
8. Reset vector is changed to 0000h.
9. Reset of all registers is revisited. Five different Reset (and wake-up) types are recognized. Registers are reset differently.
10. Wake-up from Sleep through interrupt is added.

11. Two separate timers, Oscillator Start-up Timer (OST) and Power-up Timer (PWRT) are included for more reliable power-up. These timers are invoked selectively to avoid unnecessary delays on power-up and wake-up.
12. PORTB has weak pull-ups and interrupt on change feature.
13. T0CKI pin is also a port pin (RA4) now.
14. FSR is made a full eight-bit register.
15. "In-circuit serial programming" is made possible. The user can program PIC16CXX devices using only five pins: VDD, VSS, MCLR/VPP, RB6 (clock) and RB7 (data in/out).
16. PCON STATUS register is added with a Power-on Reset Status bit (POR).
17. Code protection scheme is enhanced such that portions of the program memory can be protected, while the remainder is unprotected.
18. Brown-out protection circuitry has been added. Controlled by Configuration Word bit BODEN. Brown-out Reset ensures the device is placed in a Reset condition if VDD dips below a fixed setpoint.

To convert code written for PIC16C5X to PIC16CXXX, the user should take the following steps:

1. Remove any program memory page select operations (PA2, PA1, PA0 bits) for CALL, GOTO.
2. Revisit any computed jump operations (write to PC or add to PC, etc.) to make sure page bits are set properly under the new scheme.
3. Eliminate any data memory page switching. Redefine data variables to reallocate them.
4. Verify all writes to STATUS, OPTION, and FSR registers since these have changed.
5. Change Reset vector to 0000h.

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PIC16C712/716 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	-XX	X	/XX	XXX
Device	Frequency Range	Temperature Range	Package	Pattern
Device: PIC16C712 ⁽¹⁾ , PIC16C712T ⁽²⁾ ; VDD range 4.0V to 5.5V PIC16LC712 ⁽¹⁾ , PIC16LC712T ⁽²⁾ ; VDD range 2.5V to 5.5V PIC16C716 ⁽¹⁾ , PIC16C716T ⁽²⁾ ; VDD range 4.0V to 5.5V PIC16LC716 ⁽¹⁾ , PIC16LC716T ⁽²⁾ ; VDD range 2.5V to 5.5V				
Frequency Range: 04 = 4 MHz 20 = 20 MHz				
Temperature Range: blank = 0°C to 70°C (Commercial) I = -40°C to +85°C (Industrial) E = -40°C to +125°C (Extended)				
Package: JW = Windowed CERDIP SO = SOIC P = PDIP SS = SSOP				
Pattern: QTP, SQTP, Code or Special Requirements (blank otherwise)				

Examples:

- PIC16C716 – 04/P 301 = Commercial temp., PDIP package, 4 MHz, normal VDD limits, QTP pattern #301.
- PIC16LC712 – 04I/SO = Industrial temp., SOIC package, 200 kHz, Extended VDD limits.
- PIC16C712 – 20I/P = Industrial temp., PDIP package, 20MHz, normal VDD limits.

Note 1: C = CMOS
LC = Low Power CMOS
2: T = in tape and reel – SOIC, SSOP packages only.
3: LC extended temperature device is not offered.
4: LC is not offered at 20 MHz

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type (including LC devices).

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- Your local Microchip sales office
- The Microchip Worldwide Site (www.microchip.com)